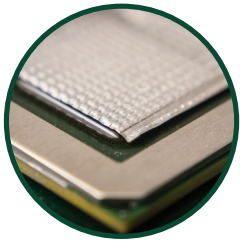


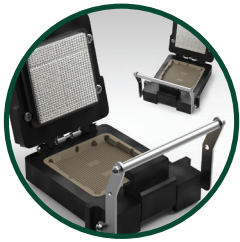
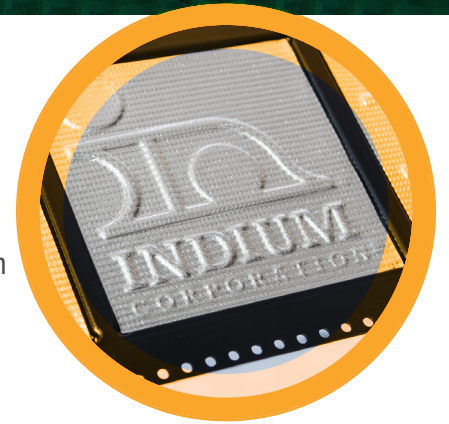
# HIGH-PERFORMANCE THERMAL INTERFACE MATERIALS

Indium Corporation is the leader in metal thermal interface materials (TIMs).



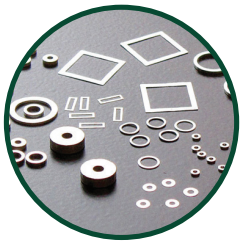
## Heat-Spring®

A Heat-Spring® is a compressible metal interface between a heat source and a heat-sink. The surface of a Heat-Spring® is patterned to optimize performance and is ideal for TIM2 and liquid immersion cooling applications.



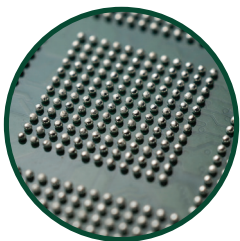
## Indium TIM for Burn-In

Because of its high thermal conductivity (86W/mK), indium is used for a variety of demanding burn-in and test applications. The pure indium can be clad with a thin aluminum layer on the side facing the DUT to prevent the soft metal from adhering to the surface.



## Solder TIM Solutions

Reflowed solder joints are also thermally conductive because of the intermetallic bond that is created. Because the material is reflowed, it will help reduce voiding, which can impede thermal conductivity.



## Solder TIM Solutions for BGAs

Revolutionary new manufacturing processes enable uniform distributions of IMCs ensuring consistent reflow and void performance over multiple reflow cycles.



## Liquid Metal Paste

Unlike traditional gallium-based liquid metal which is prone to pump-out and typically requires specialized spreading processes, liquid metal paste has a higher viscosity that offers predictable spreading characteristics required for scalable high-volume applications.

Contact our engineers: [jmajor@indium.com](mailto:jmajor@indium.com)  
Learn more: [www.indium.com/TIMs](http://www.indium.com/TIMs)

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.  
Indium Corporation is an ISO 9001:2015 registered company.

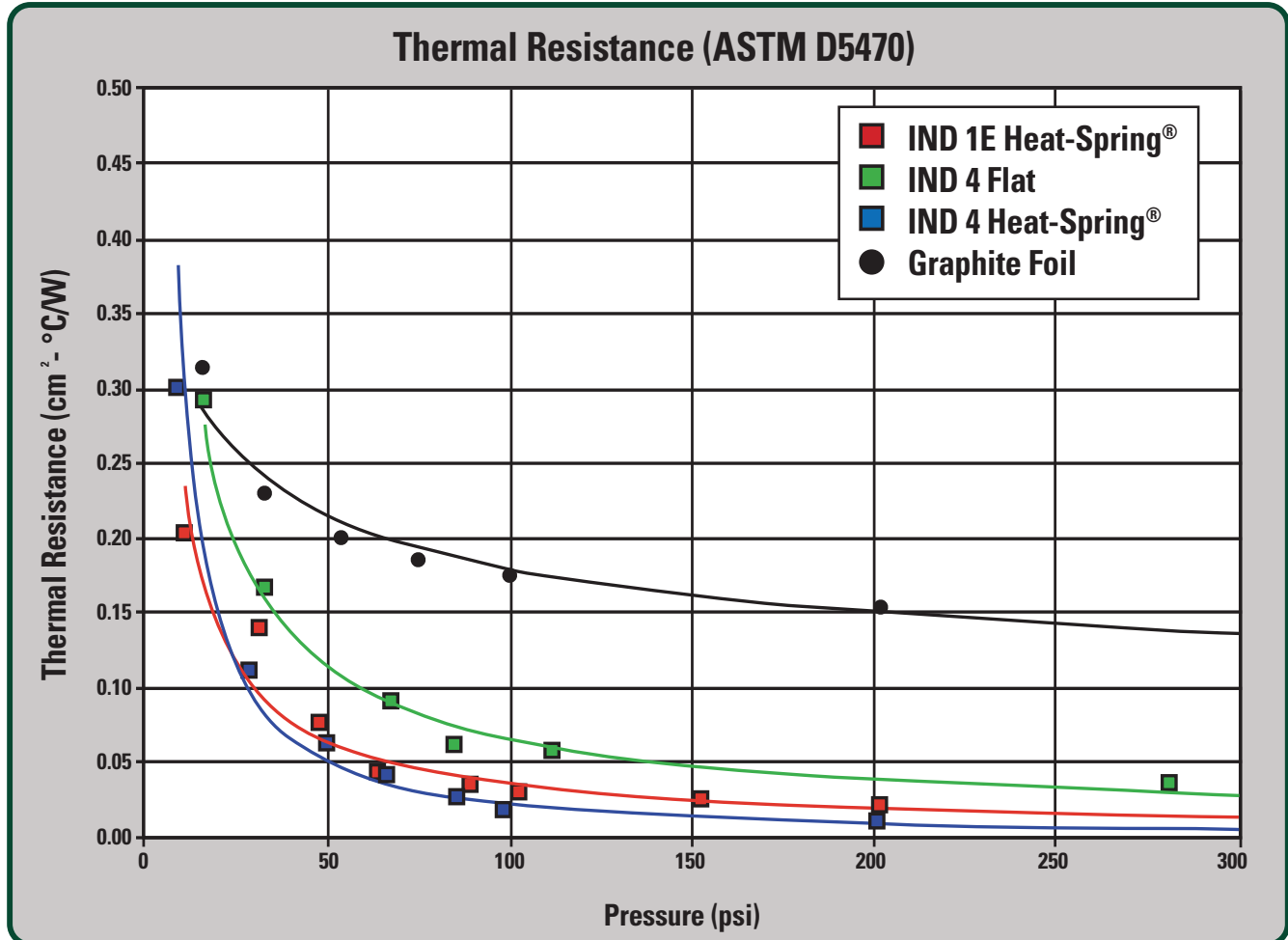
**From One Engineer To Another®**

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# HIGH-PERFORMANCE THERMAL INTERFACE MATERIALS



- High in thermal conductivity
- Easy to handle—easy clean-up
- Silicone-free
- Reclaimable and recyclable
- Free from outgassing, bake-out, and pump-out
- Able to compensate for up to 75µm of warpage
- Low cost of ownership

Contact our engineers: [jmajor@indium.com](mailto:jmajor@indium.com)

Learn more: [www.indium.com/TIMs](http://www.indium.com/TIMs)

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